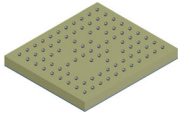


MECHANICAL CASE OUTLINE

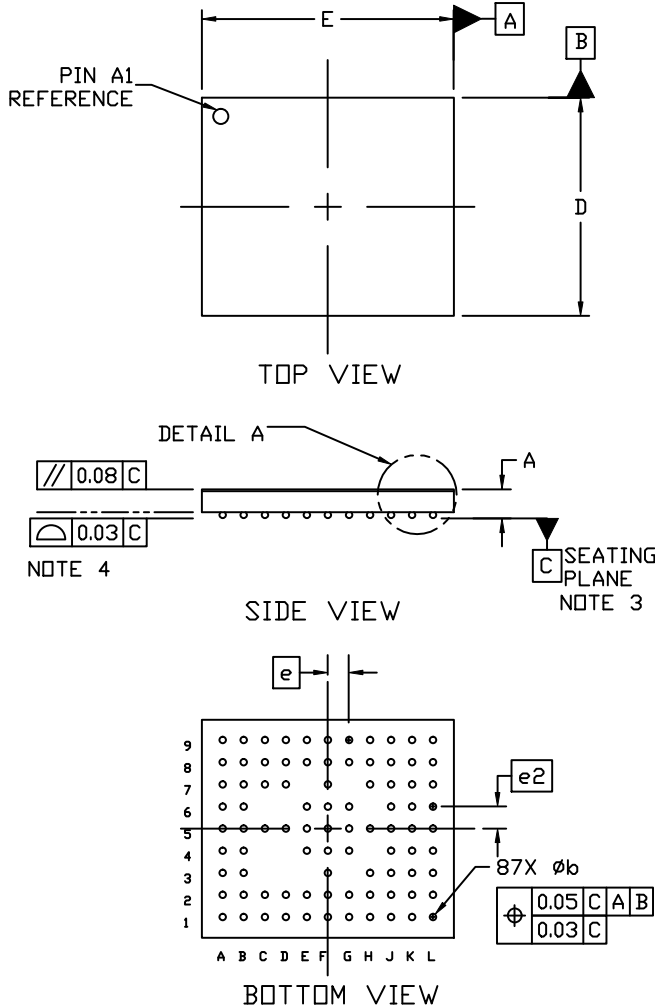
PACKAGE DIMENSIONS

ON Semiconductor®



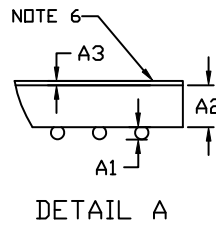
WLCSP87 2.643x3.053x0.354
CASE 567ZN
ISSUE B

DATE 24 MAY 2021

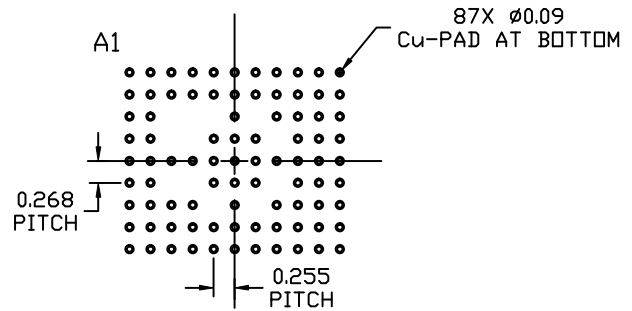


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION *b* IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.329	0.354	0.379
A1	0.060	0.075	0.090
A2	0.241	0.254	0.267
A3	0.025 REF		
<i>b</i>	0.087	0.102	0.117
D	2.593	2.643	2.693
E	3.003	3.053	3.103
<i>e</i>	0.255 BSC		
<i>e2</i>	0.268 BSC		



RECOMMENDED MOUNTING FOOTPRINT*
(NSMD PAD TYPE)

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 YY = Year
 WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "C" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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